

News advisory



HP Delivers Breakthrough BladeSystem c-Class Portfolio

As data centers strive to become more efficient, IT infrastructure costs are rising and infrastructure tasks are becoming more time-consuming. An innovator in the high end server and server blade market, HP has addressed these critical issues with its new breakthrough, modular infrastructure solution.

The new HP BladeSystem c-Class portfolio consolidates power, cooling, connectivity, redundancy and security into a modular, self-tuning system with built-in intelligence. It can be filled with a variety of modular components to build solutions for any business where any element can be "bladed," including storage, server, client and networking. With its many innovations inside, it addresses the leading pain points and cost drivers of today's large data centers and small server rooms – time, energy and change.

Adaptive Infrastructure for data center challenges

The new blade architecture will help businesses of all sizes significantly lower IT capital and operational costs and increase responsiveness to change. Under development for more than three years, the groundbreaking HP BladeSystem c-Class portfolio is the first blade architecture that enables customers to wire computing resources once and change on the fly, dynamically adjust power and cooling to meet energy budgets, and increase administrative productivity up to tenfold.

The architecture is designed to support HP ProLiant and Integrity blade servers, HP StorageWorks storage offerings and client blades with applications and third-party products to build complete business solutions. All modular components, as well as power and cooling technologies, are consolidated into a single enclosure, connected by an intelligent backplane and controlled with HP management.

A milestone in the industry, the HP BladeSystem c-Class portfolio accelerates the IT industry trend away from monolithic systems to more modular, flexible building blocks, beginning with a new enclosure and new blade servers.

The first modular components for the new HP BladeSystem c-Class portfolio include:

- HP BladeSystem c7000 Enclosure – Provides the foundation for a new modular computing architecture that consolidates and simplifies infrastructure, reduces operational cost and delivers IT services more effectively to the business. Redesigned from the start to deliver a bold

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agenda for the future of blade computing, it integrates exclusive HP innovations to tackle the toughest problems facing IT infrastructures – cost, time, energy and change;

- HP ProLiant BL460c server blade – Power efficient server blade that doubles the features of standard server blades to deliver required enterprise performance and availability in half the space for network infrastructure, web applications and high-performance computing applications. The BL460c features eight DIMMS – two times as many as the IBM HS20 – more I/O expansion and supports two more blades in each enclosure compared to the IBM BladeCenter;
- HP ProLiant BL480c server blade – The only dual-processor Intel® Xeon™ server blade with 12 DIMM slots – three times as many as the IBM HS20 – designed to expand the computing workloads possible with server blades. With a combination of enterprise-class features, performance and scalability, the BL480c is the first blade of its kind to support a wide variety of demanding applications and virtualized environments from database to web applications versus competitive blades.

Unlike other server blade choices, all HP ProLiant c-Class server blades include hot-plug drives for better redundancy and easy servicing. Each HP server blade also includes Integrated Lights-Out management processor 2 (iLO 2) for fast and easy remote management. Versus competing server blades, they include more than double the memory – 32 gigabit (GB) to 48 GB of DDR2 memory – and more than double the I/O expansion slots ideal for demanding workloads and virtual environments.

Pricing and availability

The HP BladeSystem c-Class portfolio is expected to be available in July, with pricing available at that time.

More information on HP BladeSystem c-Class portfolio is available at www.hp.com/go/bladesystem/evaluate. More information about HP BladeSystem technology is available at www.hp.com/go/bladesystem.

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